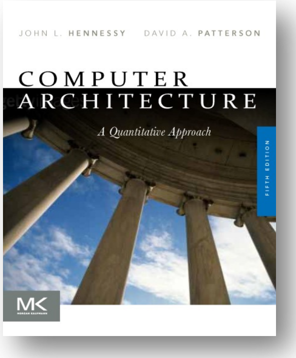
Computer Architecture

A Quantitative Approach, Fifth Edition



# Chapter 1

## Fundamentals of Quantitative Design and Analysis

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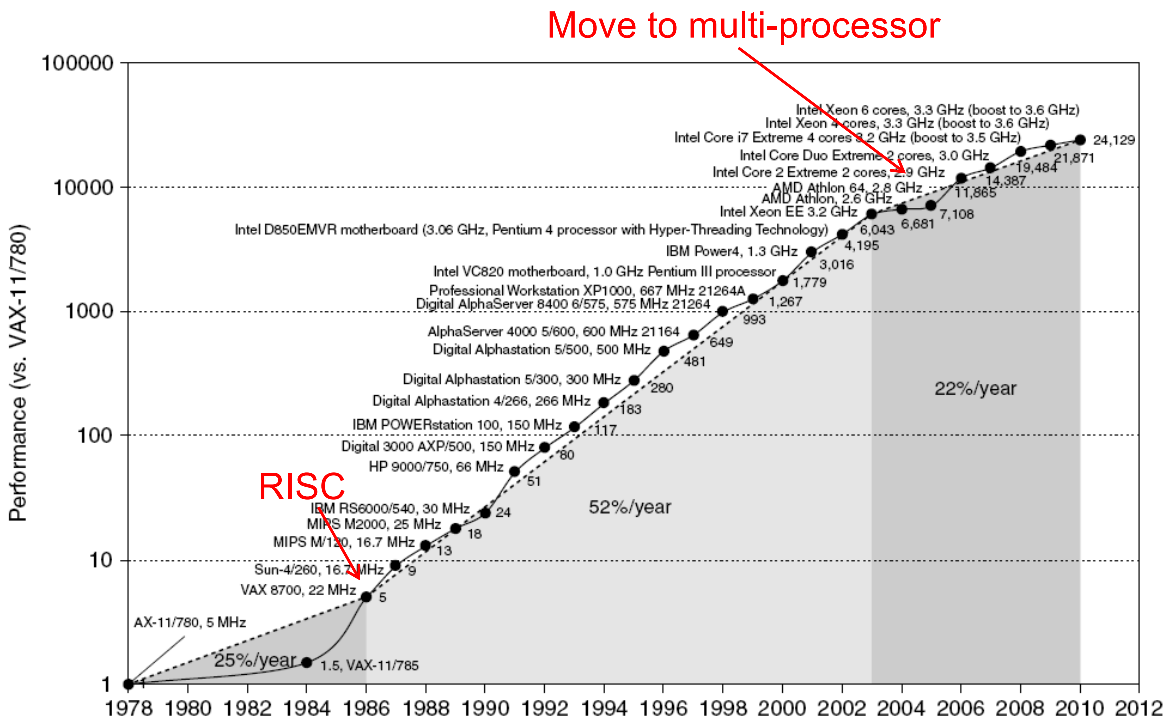
# Computer Technology

- Performance improvements:
  - Improvements in semiconductor technology
    - Feature size, clock speed
  - Improvements in computer architectures
    - Enabled by HLL compilers, UNIX
    - Lead to RISC architectures

  - Together have enabled:
    - Lightweight computers
    - Productivity-based managed/interpreted programming languages

# Single Processor Performance



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# Current Trends in Architecture

- Cannot continue to leverage Instruction-Level parallelism (ILP)
  - Single processor performance improvement ended in 2003

- New models for performance:
  - Data-level parallelism (DLP)
  - Thread-level parallelism (TLP)
  - Request-level parallelism (RLP)

- These require explicit restructuring of the application

# Classes of Computers

- Personal Mobile Device (PMD)
  - e.g. start phones, tablet computers
  - Emphasis on energy efficiency and real-time
- Desktop Computing
  - Emphasis on price-performance
- Servers
  - Emphasis on availability, scalability, throughput
- Clusters / Warehouse Scale Computers
  - Used for "Software as a Service (SaaS)"
  - Emphasis on availability and price-performance
  - Sub-class: Supercomputers, emphasis: floating-point performance and fast internal networks
- Embedded Computers
  - Emphasis: price

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# Parallelism

- Classes of parallelism in applications:
  - Data-Level Parallelism (DLP)
  - Task-Level Parallelism (TLP)

- Classes of architectural parallelism:
  - Instruction-Level Parallelism (ILP)
  - Vector architectures/Graphic Processor Units (GPUs)
  - Thread-Level Parallelism
  - Request-Level Parallelism

# Flynn’s Taxonomy

- Single instruction stream, single data stream (SISD)
- Single instruction stream, multiple data streams (SIMD)
  - Vector architectures
  - Multimedia extensions
  - Graphics processor units
- Multiple instruction streams, single data stream (MISD)
  - No commercial implementation
- Multiple instruction streams, multiple data streams (MIMD)
  - Tightly-coupled MIMD
  - Loosely-coupled MIMD

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# Defining Computer Architecture

- “Old” view of computer architecture:
  - Instruction Set Architecture (ISA) design
  - i.e. decisions regarding:
    - registers, memory addressing, addressing modes, instruction operands, available operations, control flow instructions, instruction encoding
- “Real” computer architecture:
  - Specific requirements of the target machine
  - Design to maximize performance within constraints: cost, power, and availability
  - Includes ISA, microarchitecture, hardware

# Trends in Technology

- Integrated circuit technology
  - Transistor density: 35%/year
  - Die size: 10-20%/year
  - Integration overall: 40-55%/year
- DRAM capacity: 25-40%/year (slowing)
- Flash capacity: 50-60%/year
  - 15-20X cheaper/bit than DRAM
- Magnetic disk technology: 40%/year
  - 15-25X cheaper/bit then Flash
  - 300-500X cheaper/bit than DRAM

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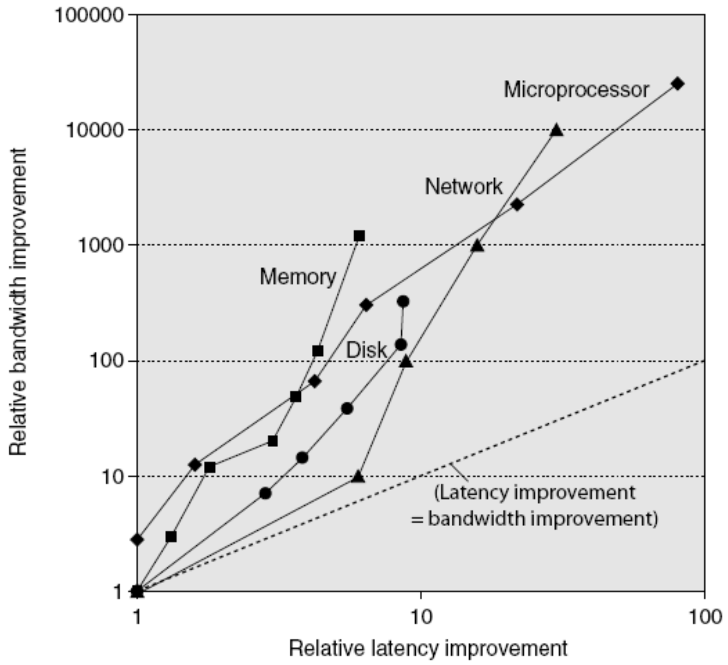
# Bandwidth and Latency

- Bandwidth or throughput
  - Total work done in a given time
  - 10,000-25,000X improvement for processors
  - 300-1200X improvement for memory and disks
- Latency or response time
  - Time between start and completion of an event
  - 30-80X improvement for processors
  - 6-8X improvement for memory and disks

# Bandwidth and Latency



Log-log plot of bandwidth and latency milestones

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# Transistors and Wires

- Feature size
  - Minimum size of transistor or wire in x or y dimension
  - 10 microns in 1971 to .032 microns in 2011
  - Transistor performance scales linearly
    - Wire delay does not improve with feature size!
  - Integration density scales quadratically

# Power and Energy

- Problem: Get power in, get power out
- Thermal Design Power (TDP)
  - Characterizes sustained power consumption
  - Used as target for power supply and cooling system
  - Lower than peak power, higher than average power consumption
- Clock rate can be reduced dynamically to limit power consumption
- Energy per task is often a better measurement

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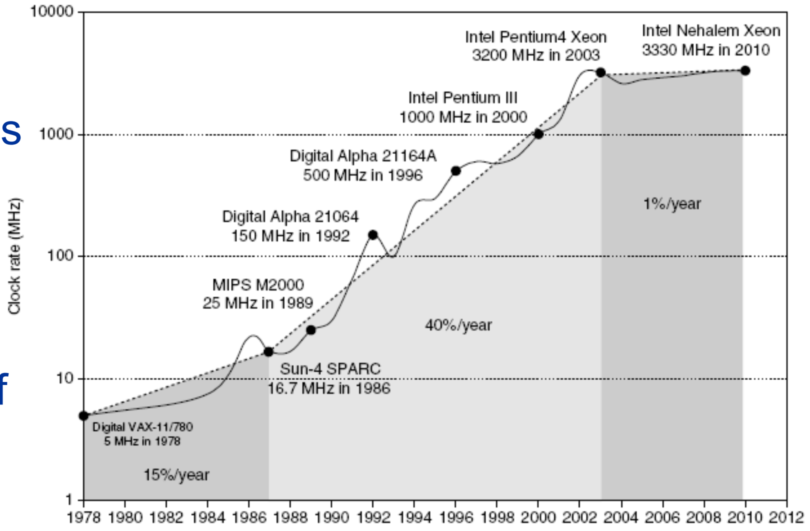
# Dynamic Energy and Power

- Dynamic energy
  - Transistor switch from 0 -> 1 or 1 -> 0
  - ½ x Capacitive load x Voltage$^2$
- Dynamic power
  - ½ x Capacitive load x Voltage$^2$ x Frequency switched
- Reducing clock rate reduces power, not energy

# Power

- Intel 80386 consumed ~ 2 W
- 3.3 GHz Intel Core i7 consumes 130 W
- Heat must be dissipated from 1.5 x 1.5 cm chip
- This is the limit of what can be cooled by air



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# Reducing Power

- Techniques for reducing power:
  - Do nothing well
  - Dynamic Voltage-Frequency Scaling
  - Low power state for DRAM, disks
  - Overclocking, turning off cores

# Static Power

- Static power consumption
  - $\text{Current}_{\text{static}}$ x Voltage
  - Scales with number of transistors
  - To reduce: power gating

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# Trends in Cost

- Cost driven down by learning curve
  - Yield

- DRAM: price closely tracks cost

- Microprocessors: price depends on volume
  - 10% less for each doubling of volume

# Integrated Circuit Cost

- Integrated circuit

$$\text{Cost of integrated circuit} = \frac{\text{Cost of die} + \text{Cost of testing die} + \text{Cost of packaging and final test}}{\text{Final test yield}}$$

$$\text{Cost of die} = \frac{\text{Cost of wafer}}{\text{Dies per wafer} \times \text{Die yield}}$$

$$\text{Dies per wafer} = \frac{\pi \times (\text{Wafer diameter}/2)^2}{\text{Die area}} - \frac{\pi \times \text{Wafer diameter}}{\sqrt{2 \times \text{Die area}}}$$

- Bose-Einstein formula:

$$\text{Die yield} = \text{Wafer yield} \times 1/(1 + \text{Defects per unit area} \times \text{Die area})^N$$

- Defects per unit area = 0.016-0.057 defects per square cm (2010)
- N = process-complexity factor = 11.5-15.5 (40 nm, 2010)

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# Dependability

- Module reliability
    - Mean time to failure (MTTF)
    - Mean time to repair (MTTR)
    - Mean time between failures (MTBF) = MTTF + MTTR
    - Availability = MTTF / MTBF

# Measuring Performance

- Typical performance metrics:
  - Response time
  - Throughput

- Speedup of X relative to Y
  - Execution time$_Y$ / Execution time$_X$

- Execution time
  - Wall clock time:  includes all system overheads
  - CPU time:  only computation time

- Benchmarks
  - Kernels (e.g. matrix multiply)
  - Toy programs (e.g. sorting)
  - Synthetic benchmarks (e.g. Dhrystone)
  - Benchmark suites (e.g. SPEC06fp, TPC-C)

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# Principles of Computer Design

- Take Advantage of Parallelism
  - e.g. multiple processors, disks, memory banks, pipelining, multiple functional units

- Principle of Locality
  - Reuse of data and instructions

- Focus on the Common Case
  - Amdahl’s Law

$$\text{Execution time}_{\text{new}} = \text{Execution time}_{\text{old}} \times \left( (1 - \text{Fraction}_{\text{enhanced}}) + \frac{\text{Fraction}_{\text{enhanced}}}{\text{Speedup}_{\text{enhanced}}} \right)$$

$$\text{Speedup}_{\text{overall}} = \frac{\text{Execution time}_{\text{old}}}{\text{Execution time}_{\text{new}}} = \frac{1}{(1 - \text{Fraction}_{\text{enhanced}}) + \dfrac{\text{Fraction}_{\text{enhanced}}}{\text{Speedup}_{\text{enhanced}}}}$$

# Principles of Computer Design

- The Processor Performance Equation

$$\text{CPU time} = \text{CPU clock cycles for a program} \times \text{Clock cycle time}$$

$$\text{CPU time} = \frac{\text{CPU clock cycles for a program}}{\text{Clock rate}}$$

$$\text{CPI} = \frac{\text{CPU clock cycles for a program}}{\text{Instruction count}}$$

$$\text{CPU time} = \text{Instruction count} \times \text{Cycles per instruction} \times \text{Clock cycle time}$$

$$\frac{\text{Instructions}}{\text{Program}} \times \frac{\text{Clock cycles}}{\text{Instruction}} \times \frac{\text{Seconds}}{\text{Clock cycle}} = \frac{\text{Seconds}}{\text{Program}} = \text{CPU time}$$

# Principles of Computer Design

- Different instruction types having different CPIs

$$\text{CPU clock cycles} = \sum_{i=1}^{n} \text{IC}_i \times \text{CPI}_i$$

$$\text{CPU time} = \left( \sum_{i=1}^{n} \text{IC}_i \times \text{CPI}_i \right) \times \text{Clock cycle time}$$